

## **REMARKS**

Claims 2-56 are in this application. Claim 1 has been cancelled and claims 52-56 are new. The election of claims 1-33 is affirmed and Claims 34-51 are withdrawn.

Claim 1 has been replaced by new claim 52. Support for new claim 52 is based at least on original claim 1 and claim 4. . Claim 52 provides for a printed circuit board including an insulation-material base body and a metal lamination as a conductor layer. Claim 52 provides that the conductive layer of the thin-film assembly is smoothed having a surface roughness of at most 10nm. In addition, the contact layer is physically or chemically adsorbed on the surface of the base electrode. Such a contact layer is not disclosed in the cited prior art. Claim 53 is based on the previous version of claim 8; claim 54 is based on the previous version of claim 9; claim 55 is based on the previous version of claim 12 and claim 56 is based on the previous version of claim 28.

According to the Office Action, claims 1, 5, 8-9 and 12-13 are rejected under 35 USC 102(b) as being anticipated by Izumi (US20020123176). According to the Office Action, claims 2-3 and 6-7 are rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Yoshimura et al. (US Patent 6845184). These are respectfully traversed.

Firstly, Izumi describes only glass substrates. Glass substrates a priori have a substantially smoother surface than conventional printed circuit board substrates made of, for example, epoxy

resins, etc. and accordingly this is not allowing conventional printed circuit boards to be used as a substrate and to provide a suitable base for thin-film components. For this purpose, the conductive layer applied to the printed circuit board substrate must be prepared in a smoothed form for the purpose of forming the base electrode so as to provide the basis for the thin-film assembly is of course unnecessary in the case of the glass substrate according to Izumi.

Secondly, the new main claim 52 incorporates subject matter of claim 4 which is not included in these rejections.

Therefore, it is respectfully requested that this rejection be withdrawn.

According to the Office Action claim 4 is rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Abe (US20030218153). This is respectfully traversed.

This combination of references does not render the smoothed conductive base layer feature obvious. Although Abe does mention a smooth surface, the smooth conductive thin-film is provided as the upper electrode in the assembly according to Fig. 7 of Abe. This is for a completely different purpose e.g. in order to insure the transparency or translucence, respectively. This has nothing to do whatsoever with the basic object of the claimed invention, namely to make when using a conventional printed circuit board as the basis-the conductive layer thereof suitable for applying an appropriate thin-film assembly.

Therefore, it is respectfully requested that this rejection be withdrawn.

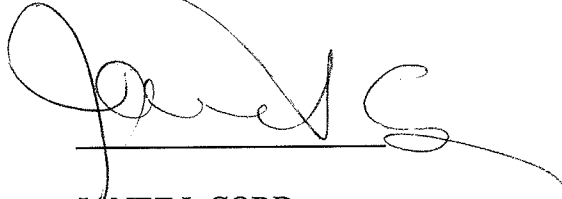
According to the Office Action claims 10-11 are rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Lin (US20020109796). According to the Office Action claims 15-23 are rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Speakman (US20030076649). According to the Office Action claim 24 is rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Speakman (US20030076649) as applied to claim 22, further in view of Ross (US5830529). According to the Office Action claim 25 is rejected under 35 USC 103(a) as being unpatentable over Izumi in view of Speakman (US20030076649) as applied to claim 23, further in view of Komoto et al. (US6674097). According to the Office Action claims 26-27 and 33 are rejected under 35 USC 103(a) as being unpatentable over Izumi in view of O'Bryan et al. (US6638378). According to the Office Action claims 28-29 and 31 are rejected under 35 USC 103(a) as being unpatentable over Izumi in view of O'Bryan et al. (US6638378) as applied to claim 26 further in view of Ottermann (US Patent 7268486). According to the Office Action claim 32 is rejected under 35 USC 103(a) as being unpatentable over Izumi in view of O'Bryan et al. (US6638378) as applied to claim 26 further in view of Takase et al. (US Patent 5463229.) These are respectfully traversed.

Based on new claim 52 and the arguments presented above, as all of these claims depend directly or indirectly on new claim 52, it is respectfully requested that these rejections be withdrawn.

It is submitted that the application is in condition for allowance and favorable consideration is respectfully requested.

If any fees are required, please authorization to charge deposit account 12-0425 is provided.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Janet I. Cord', written over a horizontal line.

JANET I. CORD  
LADAS & PARRY LLP  
26 WEST 61ST STREET  
NEW YORK, NEW YORK 10023  
REG. NO.33778 (212)708-1935